

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,852,017 B2
APPLICATION NO. : 09/910638
DATED : February 8, 2005
INVENTOR(S) : Nathan R. Brown

Page 1 of 3

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Title Page		
Item (56), U.S. Patent Documents	[Omitted references]	--6,290,572 B1 9/2001 Hofmann.....451/5 5,769,699 6/1998 Yu.....451/528 6,135,858 10/2000 Takahashi.....451/41--
Column 3, Line 57	"the thicket portion"	--the thicker portion--
Column 8, Line 66	[Omitted claims]	--5. A method for removing material from a microelectronic substrate, comprising: providing a substrate holder that carries the microelectronic substrate and at least one membrane having a first membrane portion and a second membrane portion, the at least one membrane disposed between the substrate holder and the microelectronic substrate; engaging the microelectronic substrate with a planarizing medium; moving at least one of a first part of the microelectronic substrate and the planarizing medium relative to the other at a first rate; moving at least one of a second part of the microelectronic substrate and the planarizing medium relative to the other at a second rate less than the first rate; and

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(cont'd)

removing material from the first and second parts of the microelectronic substrate at approximately equal rates by biasing the first part of the microelectronic substrate against the planarizing medium with the first membrane portion having a first thickness and biasing the second part of the microelectronic substrate against the planarizing medium with the second membrane portion having a second thickness greater than the first thickness.

6. The method of claim 5 wherein engaging the microelectronic substrate with the planarizing medium includes engaging the microelectronic substrate with a polishing pad

7. The method of claim 5 wherein moving at least one of the first part of the microelectronic substrate and the planarizing medium includes moving at least one of a first annular part of the microelectronic substrate and the planarizing medium, further wherein moving at least one of the second part of the microelectronic substrate and the planarizing medium includes moving at least one of the planarizing medium and a second annular part of the microelectronic substrate positioned radially inwardly from the first annular part of the microelectronic substrate.

8. The method of claim 5 wherein the at least one membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

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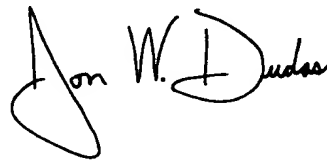
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9. The method of claim 5 wherein biasing the microelectronic substrate against a planarizing medium includes biasing the microelectronic substrate against a first portion of a polishing pad, further wherein moving at least one of the microelectronic substrate and the planarizing medium includes advancing the polishing pad from a supply roller to a take-up roller to engage a second portion of the polishing pad with the first and second parts of the microelectronic substrate.--

Signed and Sealed this

Twenty-sixth Day of December, 2006

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a cursive "Dudas".

JON W. DUDAS
Director of the United States Patent and Trademark Office